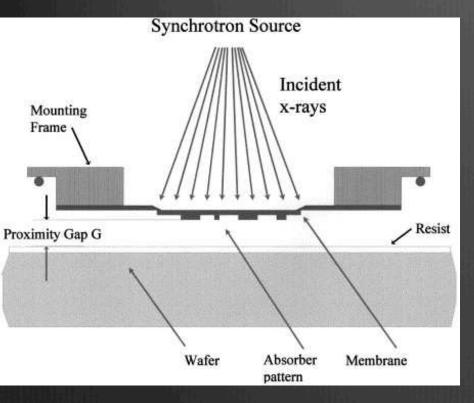
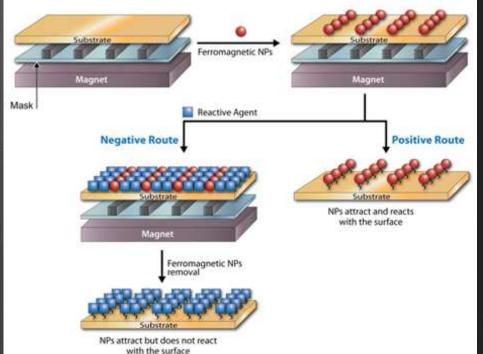
## Fabrication Technologies

Jiong Xue Hanyun Tao Yuki Krolicki September 24<sup>th</sup>, 2013

## Lithography Types

#### Other lithography methods besides photolithography discussed in lecture:





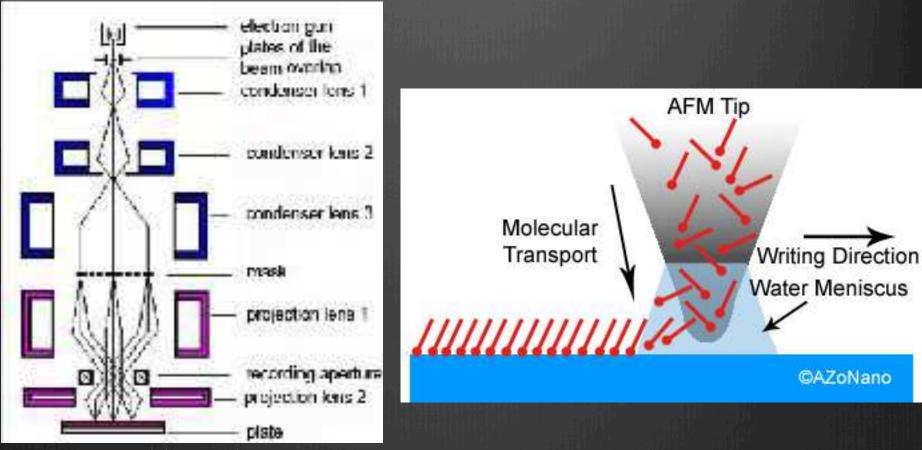
X-Ray Lithography

Able to achieve smaller scale than photolithography with shorter wavelenght
Expensive mask

### Magnetolithography

- Ferromagnetic material = photoresist,
   Paramagnetic mask = photomask
- · Can pattern non-flat surfaces

## Lithography Types



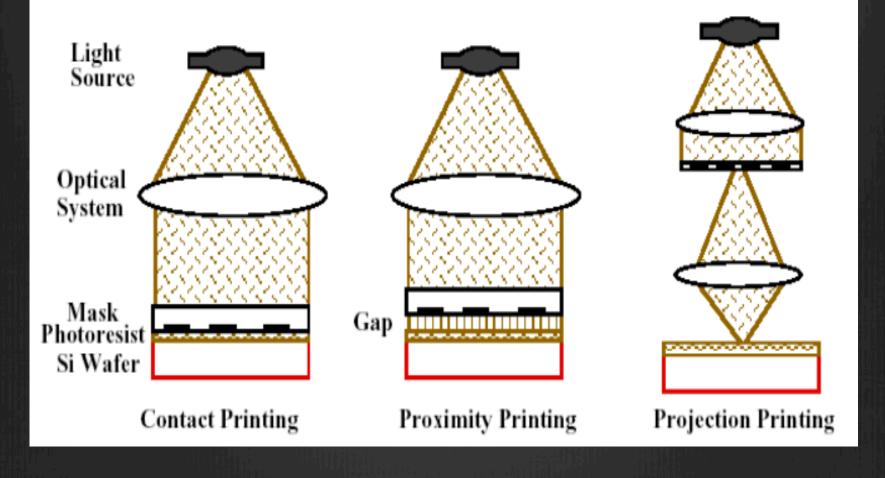
Electron Beam Lithography

- Very precise, and no mask required (direct writing)
- Slow production. Mostly used for making photomasks.

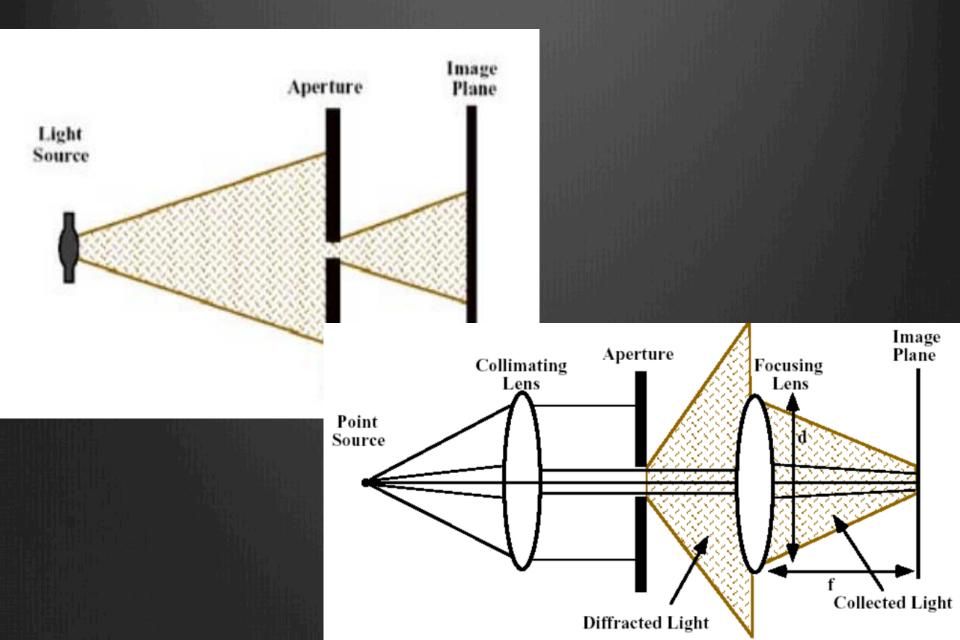
Dip-Pen Nanolithography

- Can pattern non-traditional materials using Atomic Force Microscope tip
- Environment sensitive (temperature, humidity, etc.)

### Photolithography Exposure Systems



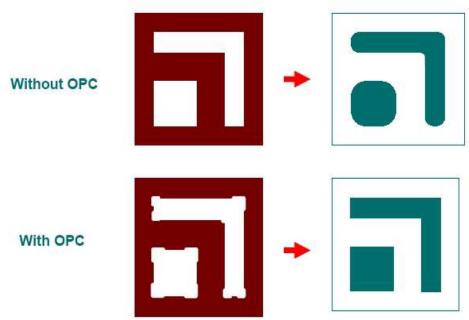
### Distortion



# Optical Proximity Correction (OPC)

### Systematic Error

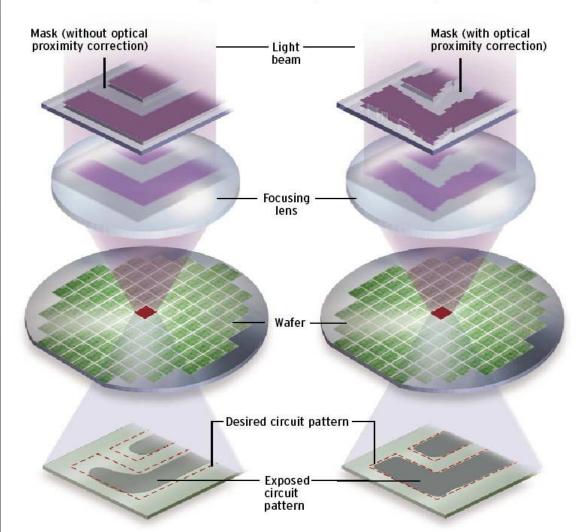
OPC mask attempt to reverse the situation by having a distorted image on the mask that is design to, produce a perfect image on the resist.



### **Optical Proximity Correction**

### Squaring the Corners

Rounded corners and shortened lines [left] are typical of the distorting effects in the exposed pattern due to current wavelengths and feature sizes. Optical proximity correction makes subresolution changes in the shape of the pattern on the mask to counter the effects [right]: corners are squarer and lines longer.



### Thank You

## Photo References

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- http://www.azonano.com/article.aspx?ArticleID=1746
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